

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)	Attorney Docket No.: MIYOSH0008
)	
Seiichi AKAGI et al.)	Confirmation No.: 6701
)	
Serial No.: 10/598,515)	Group Art Unit: 4171
)	
Filed: September 1, 2006)	Examiner: Hannah J. PAK
)	
For: SEALANT EPOXY-RESIN MOLDING)	Date: December 15, 2008
MATERIAL, AND ELECTRONIC)	
COMPONENT DEVICE)	

AMENDMENT (B)

MAIL STOP: AMENDMENT
U.S. Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In response to the non-final Office Action mailed August 13, 2008, please amend the application identified above as follows:

Amendments to the Claims are reflected by the Listing of Claims that begins on page 2 of this paper.

Remarks/Arguments begin on page 11 of this paper.